SMT Epoxy Resin Adhesive 2217L

SKU: 390-TB2217H | Sizes: 13g/10cc Syringe, 40g/30cc Syringe

Features & Benefits

- **Easy Handling**: Optimised for syringe or screen print application in automated assembly.
- **Quick Curing**: Hardens in under 60 seconds at 150ºC.
- **Low Temperature Activation**: Heat curing begins at just 80ºC.
- **No Cobwebbing**: Ensures clean application without messy residues.
- **Excellent Heat Resistance**: Offers reliable performance even at high temperatures.
- **Meets Industry Standards**: Complies with IPC SM817 and TM-650 Method 2.4.42.1 for durability.
- **Available Sizes**: 13g or 40g options to suit various project needs.
- This adhesive features excellent viscosity and thixotropic properties, ensuring smooth dispensing and screen printing with no issues like cobwebbing or dispenser feeding problems

About the SMT Epoxy Resin Adhesive 2217L

SMT Epoxy Resin Adhesive 2217L (TB2217L) is a high-performance single-component epoxy resin adhesive designed for bonding electronic chips.
It cures at temperatures of 80ºC and above, making it ideal for automated assembly processes.
This adhesive features excellent viscosity and thixotropic properties, ensuring smooth dispensing and screen printing with no issues like cobwebbing or dispenser feeding problems.
Maintains shape after application.
2 Sizes available 13g or 40g.

Specifications

Property	Detail
Application	ESD-protected areas, electronics mfg, cleanrooms